

Sir:



011504

Transmitted herewith for filing is the Patent Application of:

Inventor: **SHIH-YEN TSAI, PO-HSIUNG LEU, CHIA-MING YANG, TSANG-YU LIU, YUH-DA FAN, CHEN-PENG FAN**

For: **SOLUTION FOR COPPER HILLOCK INDUCED BY THERMAL STRAIN WITH BUFFER ZONE FOR STRAIN**

**RELAXATION**

Enclosed are:

- ☒ **4** sheets of drawing(s) - formal.
- ☒ An assignment of the invention to **Taiwan Semiconductor Manufacturing Co.**
- ☐ An associate power of attorney ☐ Applicant claims small entity status
- ☐ Request & Certification under 35 USC 122(b)(2)(b)(i)

The filing fee has been calculated as shown below:

	(Col. 1)	(Col. 2)	OTHER THAN A SMALL ENTITY	
FOR:	NO. FILED	NO. EXTRA	RATE	FEE
BASIC FEE				\$ 770.
TOTAL CLAIMS	20 -20=	0	x 18 =	\$ 0.
INDEP CLAIMS	3 -3=	0	x 86 =	\$ 0.
			SUB TOTAL	\$ 770.
			ASSIGNMENT	\$40.
			TOTAL	\$ 810.

- ☒ Please charge my Deposit Account No. 19-0033 in the amount of **\$ 810.** A duplicate copy of this sheet is enclosed.
- ☒ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 19-0033. A duplicate copy of this sheet is enclosed.

- ☒ Any additional filing fees required under 37 CFR §1.16.
- ☒ Any patent application processing fees under 37 CFR §1.17.

Respectfully submitted,

STEPHEN B. ACKERMAN, REG. NO. 37,761

**EXPRESS MAIL CERTIFICATE**

Express Mail No. **EV385357641US**

I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to Assistant Commissioner of Patents, Alexandria, VA, 22313-1450. Applicant and/or Attorney requests the date of deposit as the Filing Date.

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